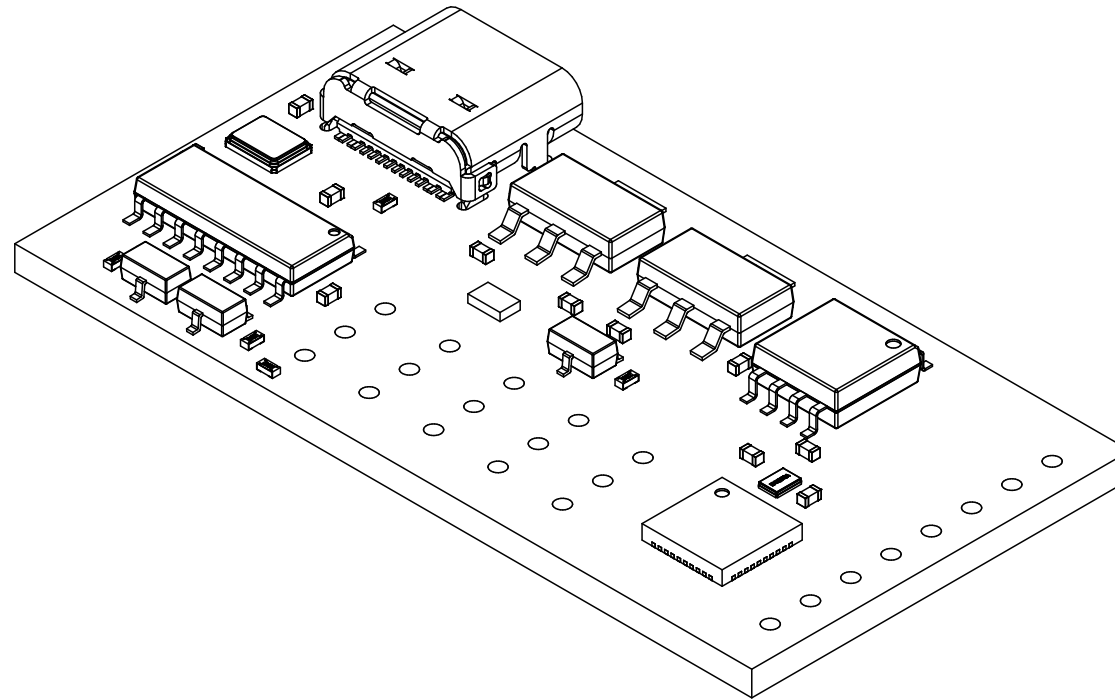
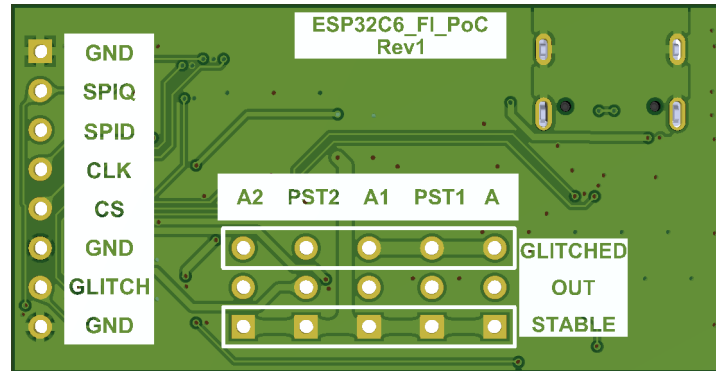
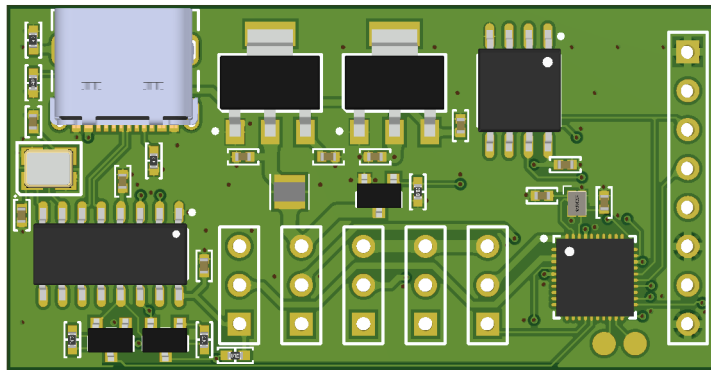
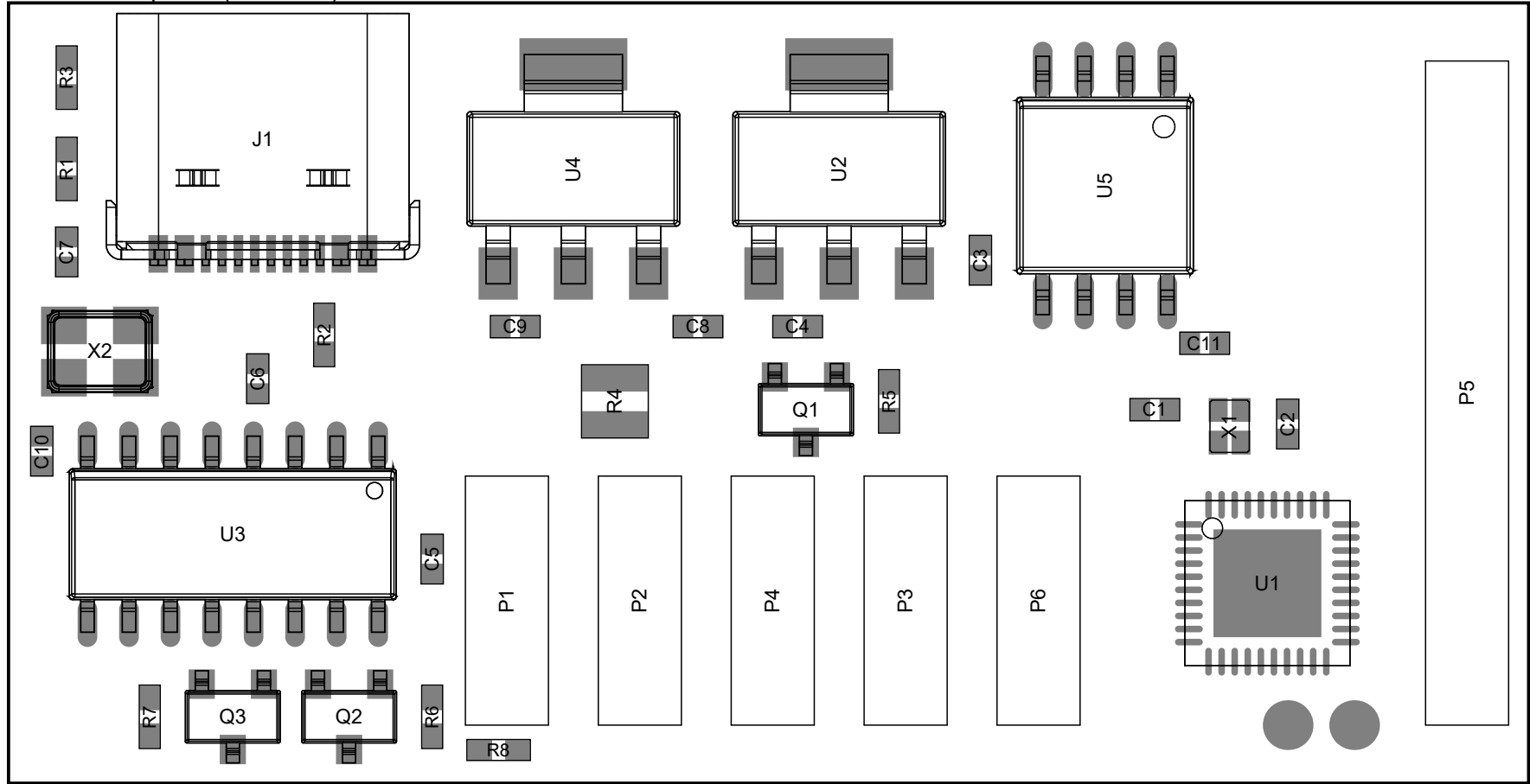


# ESP32C6\_FI\_PoC (1.0)



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View from Top side (Scale 5:1)



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Bill Of Materials

Line #	Designator	Quantity	Footprint	Tolerance	Value	Manufacturer	Material	Part Name
1	C1, C2, C5, C6	4	C0402	[NoParam], ±10%	10nF	[NoParam], Samsung Electro-Mechanics	[NoParam], X7R	C15195
2	C3, C4, C8, C9, C11	5	C0402	±10%	100nF	Samsung Electro-Mechanics	X7R	C1525
3	C7, C10	2	C0402	±5%	33pF	Guangdong Fenghua Advanced Tech	C0G	C1562
4	J1	1	USB4105-GF-A			GCT		USB4105-GF-A
5	P1, P2, P3, P4, P6	5	HDR1X3					
6	P5	1	HDR1X8					
7	Q1	1	SOT-23-3					IRLML2502
8	Q2, Q3	2	SOT-23-3-BIPOLAR			LRC		L8050QLT1G
9	R1, R2	2	R0402	±1%	5.1KΩ	Uniroyal Elec		C25905
10	R4	1	ERJB3	1%	7.5			ERJ-B3BF7R5V
11	R5, R6, R7, R8	4	R0402	±1%	10KΩ	Uniroyal Elec		C25744
12	U1	1	QFN40P500X500X90_HS-41N			Espressif		ESP32-C6
13	U2, U4	2	SOT-223					AMS1117-3.3
14	U3	1	SOP-16			Jiangsu Qin Heng		CH340G
15	U5	1	SOIC127P790X216-8N			Winbond		W25Q32JVSSIQS
16	X1	1	CRYSTAL_1_6x1_2					ABM12W-40.0000MHZ-7-B1U-T3
17	X2	1	TSX-3225			Yangxing Tech		X322512MSB4SI

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Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.020mm	Solder Resist	Solder Mask	GTS
<b>Copper</b>	<b>Top Layer</b>	<b>0.035mm</b>		<b>Signal</b>	<b>GTL</b>
Prepreg		0.099mm	PP-006	Dielectric	
CF-004	Layer 1	0.015mm		Internal Plane	GP1
		1.265mm	FR-4	Dielectric	
CF-004	Layer 2	0.015mm		Internal Plane	GP2
Prepreg		0.099mm	PP-006	Dielectric	
<b>Copper</b>	<b>Bottom Layer</b>	<b>0.035mm</b>		<b>Signal</b>	<b>GBL</b>
Surface Material	Bottom Solder	0.020mm	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO

Total thickness: 1.605mm

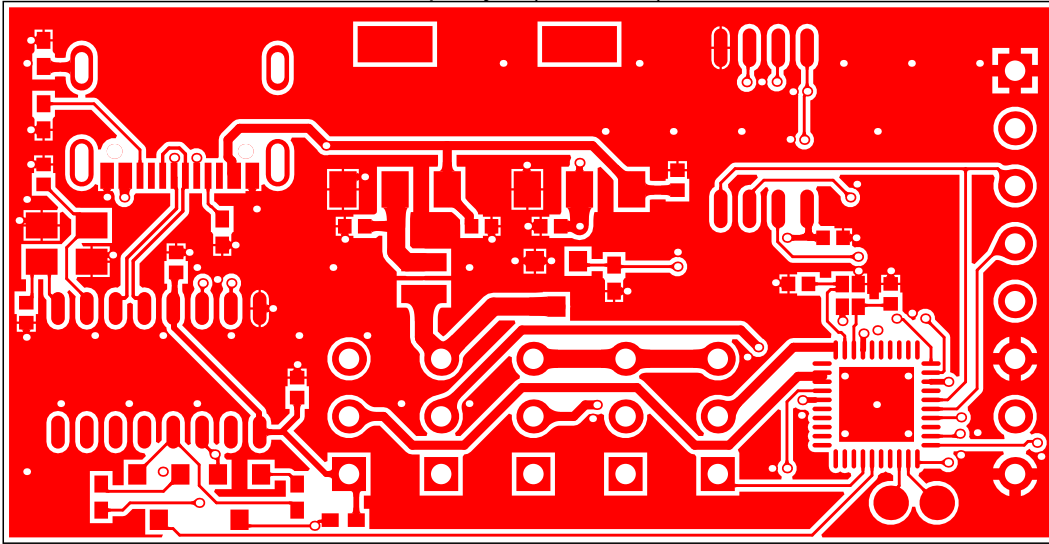
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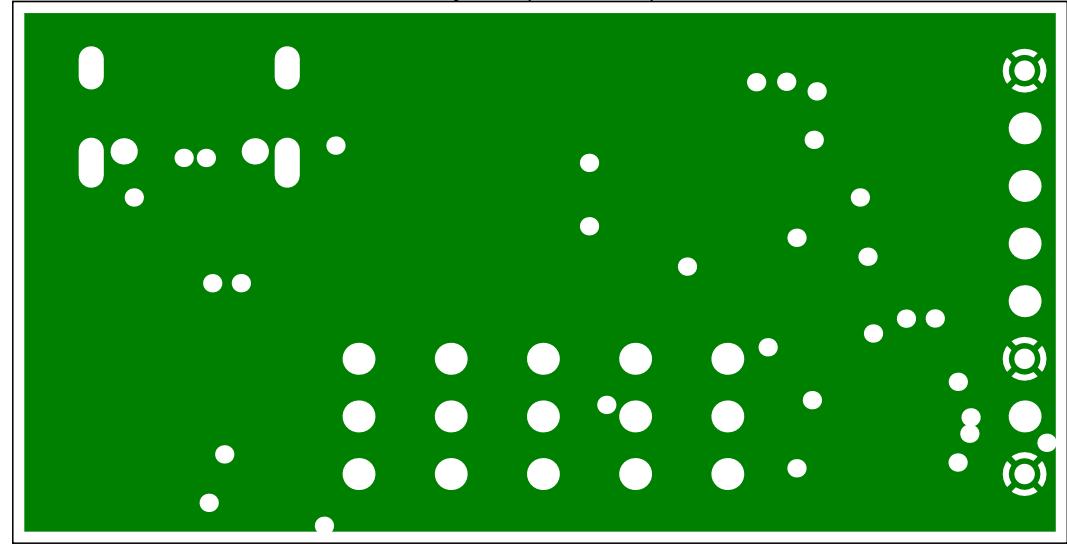
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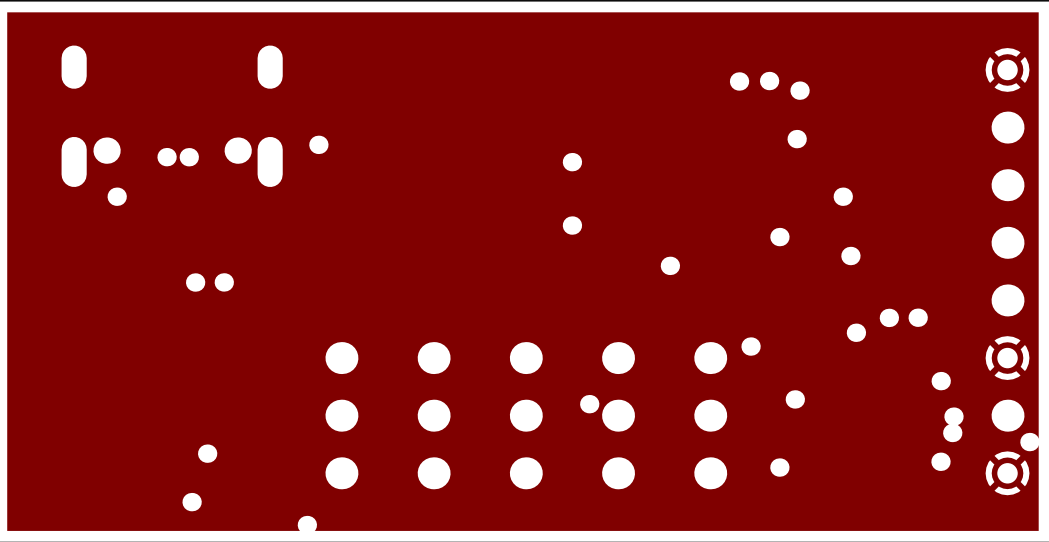
Top Layer (Scale 3:1)



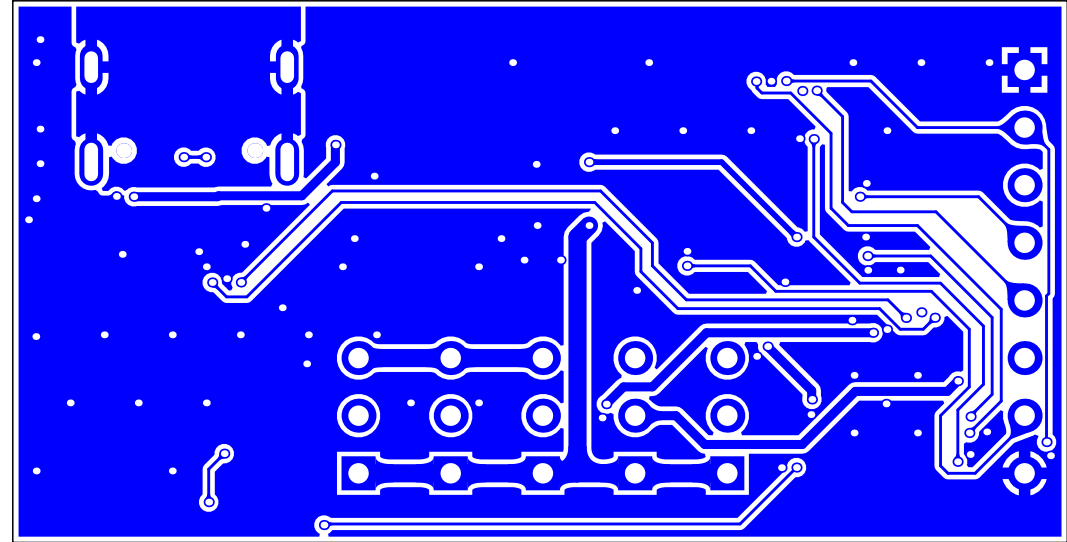
Layer 1 (Scale 3:1)




Layer 2 (Scale 3:1)



Bottom Layer (Scale 3:1)



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